

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t8410idc-1#trpbf

(Engineering Calculation)

DFN 2mm X 2mm Exp. Pad

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**TOTAL MASS (g) : 0.009122**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000571	1000000	62593.6914062		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.002935	975000	321738.15625		
		Iron (Fe)	7439-89-6	0.000072	24000	7892.72509766		
		Phosphorus (P)	7723-14-0	0.000001	300	109.621177673		
		Zinc (Zn)	7440-66-6	0.000002	700	219.242355347		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.003010</b>	<b>1000000</b>	<b>329959.75</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000136	1000000	14944.0849609		
		<b>External Plating Total:</b>				<b>0.000136</b>	<b>1000000</b>	<b>14944.0849609</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000072	1000000	7892.72509766		
<b>Internal Plating Total:</b>				<b>0.000072</b>	<b>1000000</b>	<b>7892.72509766</b>		
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000005	50000	548.105834961		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000027	300000	2959.77172852		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000059	650000	6467.64990234		
<b>Die Attach Total:</b>				<b>0.000091</b>	<b>1000000</b>	<b>9975.52734375</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000677	130000	74213.53125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.004481	860000	491212.5		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000052	10000	5700.30078125		
		<b>Encapsulation Total:</b>				<b>0.005210</b>	<b>1000000</b>	<b>571126.3125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000032	1000000	3507.87768555		
					<b>TOTAL MASS (g) :</b>	<b>0.009122</b>		